

ABSTRACT

A method for evaluating a bonding film used in a producing process of a semiconductor device, the method including a step of performing a tack test with a heated probe, in which a thickness of a bonding film to be an evaluation target is 20 μm or less. The tack test, for example, is performed by using a device including a stage for supporting a sample of the bonding film, and a probe movable with respect to the stage in an up and down direction, of which a temperature can be set, in a state of interposing a polyimide film between the stage and the sample.

Fig. 1